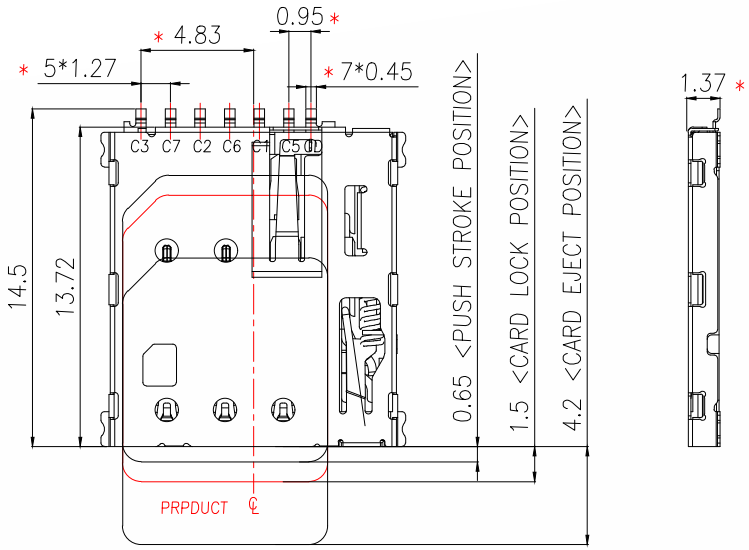
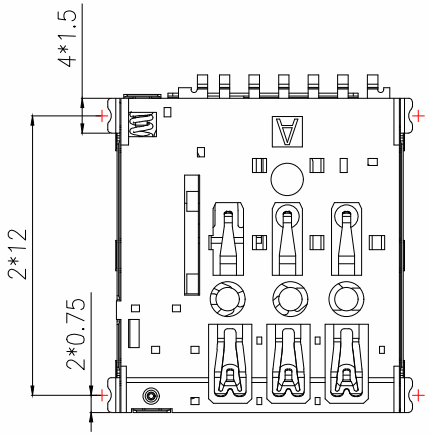
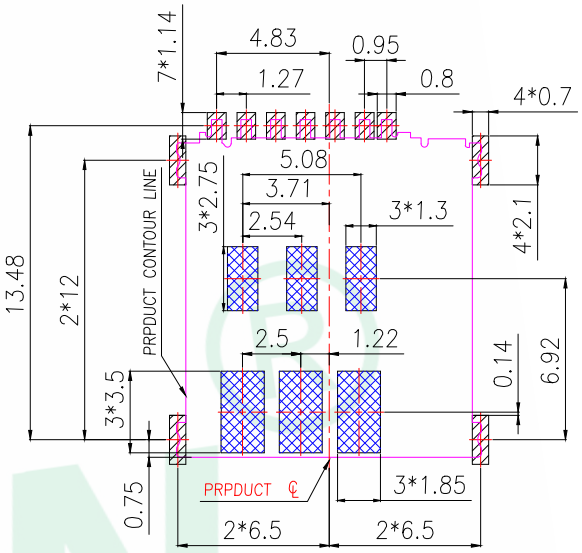
REV.	DESCRIPTION	ECN NO.	NAME	DATE





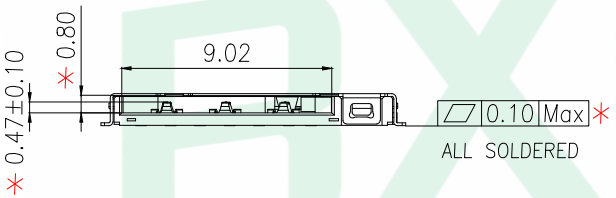


RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)

RECOMMENDED MATAL MASK T=0.12mm

SMT SOLDER AREA

NO PATTERN AND VIA HOLE IN HTIS AREA



NOTES:

1.MATERIAL:

HOUSING: High Temperature Thermoplastic

Terminal:Copper Alloy

Shell: Stainless Steel

2.PLATING:

Terminal:30u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA AND SOLDER AREA

Sheel:30u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA AND SOLDER AREA

3.TECHNICAL SPECIALITY:

RATED VOLTAGE: 30V AC MAX.

CURRENT RATING: 0.5A MAX.

INSULATION RESISTANCE:1000MΩ MIN

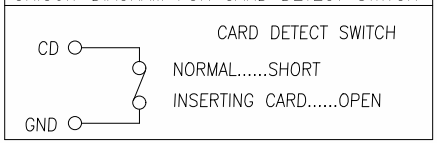
CONTACT REISTANCE:100mΩ MAX

WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES

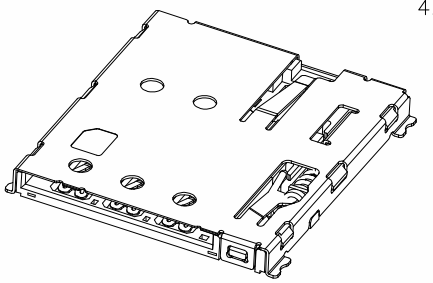
OPERATING TEMPERATURE: -40℃~+85℃Humidity 80% R.H MAX

4.DIMENSIONS WITH MARK" * "MUST BE MEASURE BY QC AND IPQC

CRICUIT DIAGRAM FOR CARD DETECT SWITCH



PIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
CD	Detect Switch
C5	GND
C6	VPP
C7	I/O



GENERAL TOLERANCE		DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD					BXCONN®
DIM.	TOL.	TITLE: NANO SIM CARD CONNECTOR(L型) 无柱 H1.37					
.x	±0.30						
.xx	±0.20						
.xxx	±0.10						
GENERAL ANGLE:		DWG. NO.: SIM304-TZ7P				CHECKED: MAX	
x.°	±3.0°						
x.x°	±2.0°	PART NO.: SIM304-TZ7P				DRAWN: ELLA	
x.xx°		UNIT: mm	SCALE: none	SHEET: 1 of 1	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL